

2SD1890

Silicon NPN triple diffusion planar type Darlington

For power amplification

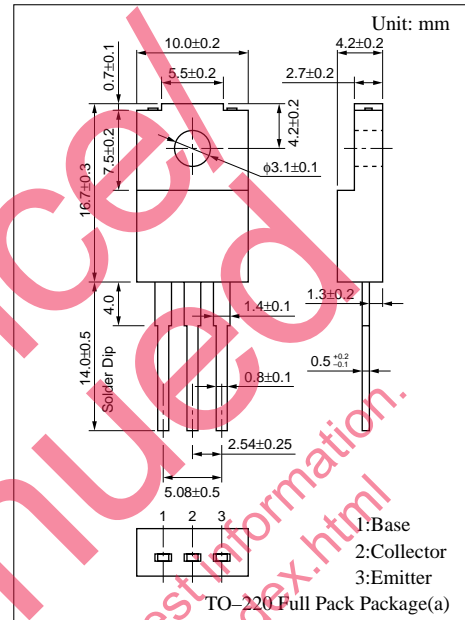
Complementary to 2SB1250

Features

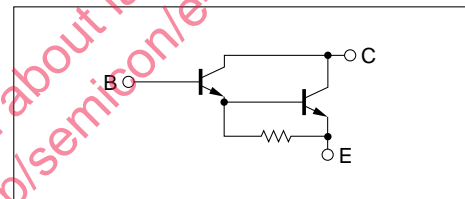
- Optimum for 25W HiFi output
- High forward current transfer ratio h_{FE} : 5000 to 30000
- Low collector to emitter saturation voltage $V_{CE(sat)}$: <2.5V
- Full-pack package which can be installed to the heat sink with one screw

Absolute Maximum Ratings ($T_C=25^\circ C$)

Parameter	Symbol	Rated	Unit
Collector to base voltage	V_{CBO}	100	V
Collector to emitter voltage	V_{CEO}	80	V
Emitter to base voltage	V_{EBO}	5	V
Peak collector current	I_{CP}	6	A
Collector current	I_C	3	A
Collector power dissipation	P_C	$T_C=25^\circ C$	35
		$T_a=25^\circ C$	2
Junction temperature	T_j	150	$^\circ C$
Storage temperature	T_{stg}	-55 to +150	$^\circ C$



Internal Connection

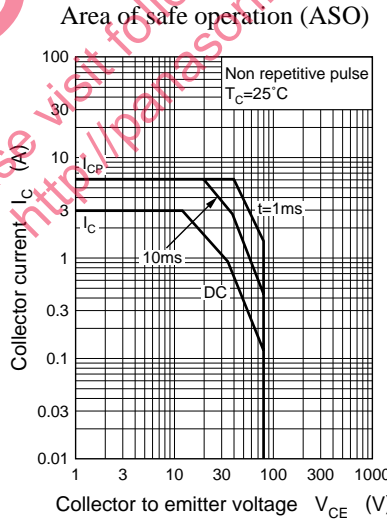
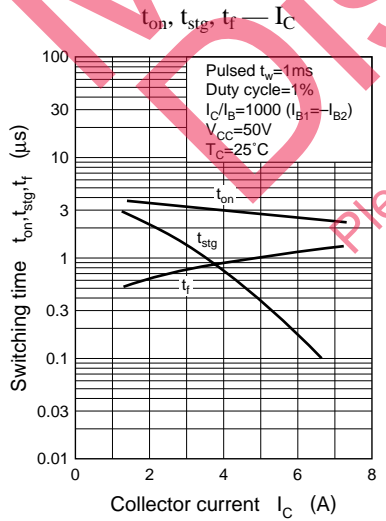
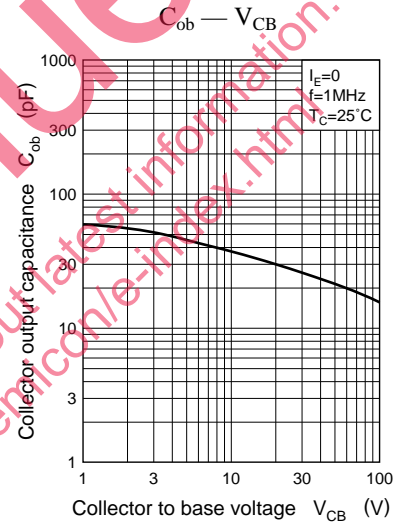
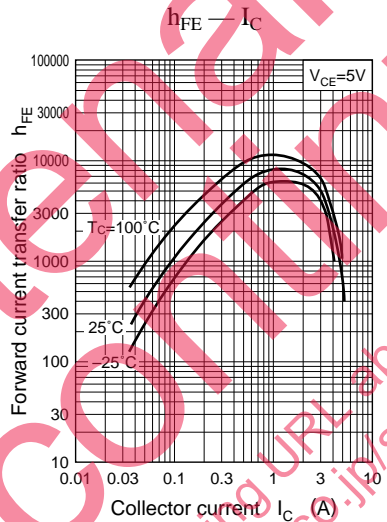
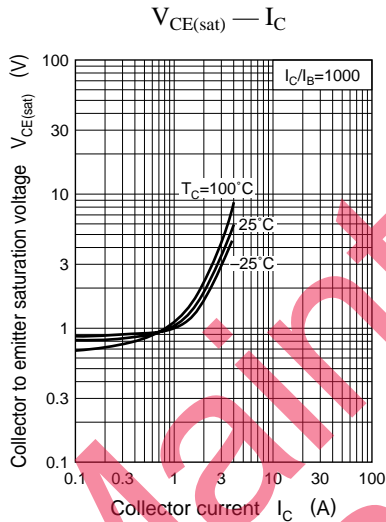
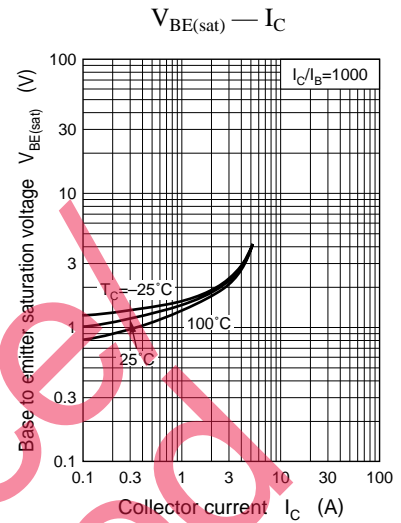
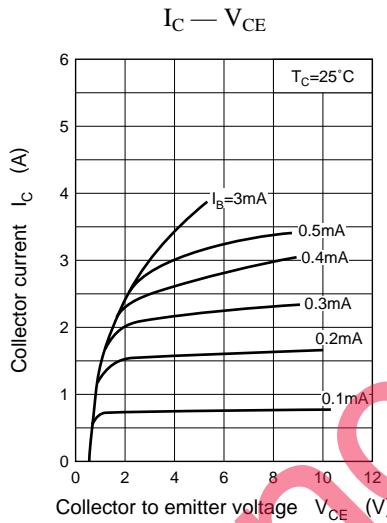
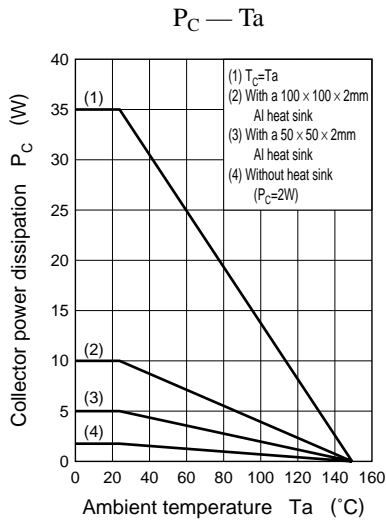


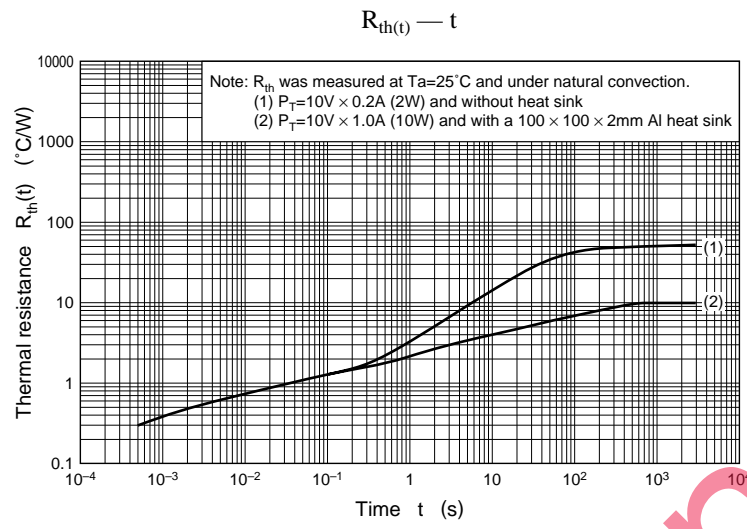
Electrical Characteristics ($T_C=25^\circ C$)

Parameter	Symbol	Conditions	min	typ	max	Unit
Collector cutoff current	I_{CBO}	$V_{CB} = 100V, I_E = 0$			100	μA
	I_{CEO}	$V_{CE} = 80V, I_B = 0$			100	μA
Emitter cutoff current	I_{EBO}	$V_{EB} = 5V, I_C = 0$			100	μA
Collector to emitter voltage	V_{CEO}	$I_C = 30mA, I_B = 0$	80			V
Forward current transfer ratio	h_{FE1}	$V_{CE} = 5V, I_C = 1A$	2000			
	h_{FE2}^*	$V_{CE} = 5V, I_C = 2A$	5000		30000	
Collector to emitter saturation voltage	$V_{CE(sat)}$	$I_C = 2A, I_B = 2mA$			2.5	V
Base to emitter saturation voltage	$V_{BE(sat)}$	$I_C = 2A, I_B = 2mA$			3.0	V
Transition frequency	f_T	$V_{CE} = 10V, I_C = 0.5A, f = 1MHz$		20		MHz
Turn-on time	t_{on}	$I_C = 2A, I_{B1} = 2mA, I_{B2} = -2mA, V_{CC} = 50V$		3.5		μs
Storage time	t_{stg}			2.5		μs
Fall time	t_f			0.6		μs

* h_{FE2} Rank classification

Rank	Q	P
h_{FE2}	5000 to 15000	8000 to 30000





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